

Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, May 19, 2012 03:55 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FSSD07UMX	FSSD07UMX	uMLP-24 (2.5x3.4)(TFSn)			INTERNAL PENANG	0.012	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Cu Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom
--	----------------------------------

RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
----------------------------------	---

Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Acceptance * Accepted
---------------------------	---	---------------------------------------

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC 0
--

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
--------------------	--

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name uMLP-24 (2.5x3.4)(TFSn)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.379	Supplier		Silicon	0.379	7440-21-3	32239
Die Attach	Other Organic Materials	0.033	Supplier		Acrylic Resin	0.010	54208-63-8	840
			Supplier		Epoxy Resin	0.023	29690-82-2	1956
Encapsulation	Thermoplastics	7.380	Supplier		Carbon Black	0.037	1333-86-4	3139
			Supplier		Epoxy Resin	1.476	129915-35-1	125553
			Supplier		Silica	5.867	60676-86-0	499073
Lead Frame	Other Ferrous alloys, non-stainless steels	2.857	Supplier		Copper	2.720	7440-50-8	231371
			Supplier		Gold	0.001	7440-57-5	72
			Supplier		Iron	0.069	7440-66-6	5833
			Supplier		Nickel	0.058	7440-31-5	4925
			Supplier		Palladium	0.005	7440-05-3	446
			Supplier		Phosphorus	0.001	7723-14-0	73
			Supplier		Zinc	0.004	7439-89-6	316
Terminal Finish	Precious metals	0.219	Supplier		Tin	0.219	7440-31-5	18629
Wire Bond	Precious metals	0.888	Supplier		Gold	0.888	7440-57-5	75536